

RH-PCM150Y

导热相变片

Thermal phase change

Features and Benefits

特点与优势

- ✦ High thermal conductivity: 1.5W/m-K
导热系数: 1.5W/M-K
- ✦ Phase change occurs at 50°~65°
在 50° ~65° 发生相变
- ✦ Comes with a certain viscosity at room temperature
常温下自带一定粘性
- ✦ No warm-up operation
无需预热操作



RH-PCM150Y It is a phase change material that has begun to soften at 50-65 °C. Compared with the traditional thermal conductive filling pad, the liquid filled pad can fill and cover the gaps and pits between the contact interfaces more effectively. On the other hand, it is in solid state at room temperature, providing convenience for assembly and use.

RH-PCM150Y 是一种在 50-65°C 已经开始软化的相变材料。液态时比传统的导热填充垫更能有效地填充及覆盖接触界面之间的缝隙和坑洼。另一方面，在室温环境下是固体形态，为组装及使用时提供操作上的便利。

The above suggestions and data are based on information that we believe to be reliable. Therefore, these suggestions and data are only for reference, not as product guarantee. It is up to the customer to decide whether the product is suitable or suitable for special use. We recommend that users first determine the suitability of our materials and recommendations before using them in large quantities.

以上建议及数据均来自我们认为可靠的资料。因此这些建议及数据仅供参考，而不作为产品保证。应由客户决定产品是否合适或适用特殊用途。我们建议用户在大量使用前，首先确定我们的材料适用性和建议。

RH-PCM150Y

| Property | Parameter | Unit | Test Method |
|------------------------------------|----------------------|-----------------------|-------------|
| Color 颜色 | 粉红色 Pink | -- | Visual |
| Thermal Conductivity 导热系数 | 1.5 | W/m.k | ASTM D5470 |
| Thickness 厚度 | 0.005" 0.127 | mm | ASTM D 751 |
| Thickness tolerance 厚度公差 | ±0.0006" ±0.016 | mm | ASTM D 751 |
| Density 密度 | 1.8 | g/cc | ASTM D792 |
| Volume Resistivity 体积电阻率 | 2.0*10 ¹³ | ohm-cm | ASTM D257 |
| Permittivity 介电常数 | 3 | @1M Hz | ASTM D150 |
| Thermal impedance 热阻抗@10psi/@10psi | 0.65 | °C-in ² /w | ASTM D5470 |
| Phase change temperature 相变化温度 | 50-65 | °C | -- |
| Fire Rating 防火等级 | V-0 | -- | UL94 |
| Working Temperature 工作温度 | -40~125 | °C | -- |
| RoHS/REACH | Compliance | -- | -- |

使用 ASTM D5470 测试夹具,记录值包括界面热阻,数值仅供参考。实际应用性能到所施加的表面粗糙度、平整度和压力。注:厚度公差:±10%, 硬度公差: ±5°, 颜色/厚度/硬度均可按顾客需求调试。

Applications

典型应用

- ✦ High frequency microprocessor 高频微处理器
- ✦ Laptop or desktop 手提或台式电脑
- ✦ Computer server, memory 计算机服务器, 存储器
- ✦ Integrated chip 集成芯片
- ✦ LED television and lighting LED 电视和照明设备

Configurations Available

产品规格

- ✦ Flake products : according to customer requirements
片状产品: 依照顾客要求
- ✦ Die-cutting products: according to customer requirements
模切产品: 依照顾客要求

Storage & Transportation: store in a ventilated, cool and dry place, do not contact with open fire. This product is non-toxic and is stored and transported as non dangerous goods.

储存&运输: 贮存于通风、阴凉、干燥处, 不要接触明火。本产品无毒, 按非危险品贮存及运输。

Packaging: customized packaging according to customer needs.

包装: 根据客户需求定制包装。

Safety: please refer to material safety performance data (MSDS) of our company

安全: 请参阅本公司《材料安全性能数据 (MSDS)》

Period of validity: the product is valid for 12 months

有效期: 本产品有效期为 12 个月